MoU/MoA

UMP and 4 industries strategic collaboration sponsors LI excellence scholarships

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KUANTAN, 22 November 2021 - Universiti Malaysia Pahang (UMP) has entered into a strategic partnership with four industries to increase graduate employability by offering UMP students an Industrial Training Excellence Scholarship.

The four companies are Nextgreen Pulp & Paper Sdn. Bhd., Chua Ming Hooi Construction Sdn. Bhd., Hardex Corporation Sdn. Bhd., and EC Excel Wire Sdn. Bhd.

The prestigious and exclusive scholarship will be offered to students who excel academically and demonstrate high leadership talent.

It will benefit students through financial support, exposure and placement of industrial training (LI) to selected students throughout their studies at UMP.

The ceremony witnessed Professor Dato' Ts. Dr. Yuserrie Zainuddin who performs the function of the Vice-Chancellor of UMP cum Deputy Chairman of Yayasan UMP and Director of the Career Placement and Development Centre (CPDC), Associate Professor Dr. Irene Ting Wei Kiong present to sign the memorandum of agreement (MoA) which took place at Hyatt Hotel Kuantan.

Also present to witness the ceremony was the Chairman of the UMP Board of Directors, Tan Sri Dato' Sri Dr. Abdul Aziz Abdul Rahman who is also the Chairman of Yayasan UMP.

Meanwhile, the industry was represented by the Managing Director of Nextgreen Pulp & Paper Sdn. Bhd., Dato' Lim Thiam Huat and Executive Director, Kelly Lim Kah Yen and Chua Ming Hooi Construction Sdn. Bhd. was represented by its Directors, Chua Say Chai and Chua Say Hand.

Bhd., Hardex Corporation Sdn. Bhd. was represented by the Managing Director, Lau Keng Chong and the Director of Operations, Goh Chung Kiat and EC Excel Wire Sdn. Bhd. was represented by the Managing Director, Ng Heng Hong and Chief Financial Officer, Hiew Yong Nin.

Tan Sri Dato' Sri Dr. Abdul Aziz expressed appreciation and gratitude to the industry for contributing scholarships to help students in need.

"Students will also benefit from practical experience oriented towards developing specific knowledge or skills in their field of study.

"They also have the opportunity to get LI placements and increase collaboration between universities and industry," he said.

The scholarship allocates RM5,000 per semester with a sponsorship funding period of eight

semesters covering tuition fees, accommodation, living allowance, book allowance and annual placement programme allowance for students.

In making this effort a success, UMP, through the Career Placement and Development Centre (CPDC), is responsible for managing career development activities and student LI placement operations for all undergraduate study programmes at UMP.

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